

# FINAL PRODUCT/PROCESS CHANGE NOTIFICATION Generic Copy

#### 04-MAY-2004

SUBJECT: ON Semiconductor Final Product/Process Change Notification #13463

TITLE: Addition of Tower Semiconductor Fab for Minigate(TM) Logic Products

**EFFECTIVE DATE: 04-Jul-2004** 

AFFECTED CHANGE CATEGORY: Subcontractor Fab Site

**AFFECTED PRODUCT DIVISION: Logic Products** 

#### ADDITIONAL RELIABILITY DATA: Available

Contact your local ON Semiconductor Sales Representative or Ken Fergus <a href="mailto:RRST50@onsemi.com">RRST50@onsemi.com</a>

**SAMPLES:** Contact your local ON Semiconductor Sales Representative or Nilda Lopez <R39140@onsemi.com>

#### FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact Sales Representative or Nilda Lopez <R39140@onsemi.com>

#### **NOTIFICATION TYPE:**

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 60 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

#### **DESCRIPTION AND PURPOSE:**

ON Semiconductor is pleased to announce expanded wafer capacity for MiniGate(TM) Logic products utilizing Tower Semiconductor. ON Semiconductor will implement this increase in capacity to support rapidly growing demand for these Logic products in an effort to assure our customers of ON Semiconductor's continued commitment to assured supply, on time delivery and continuous quality improvement.

The products will be redesigned using Tower Semiconductor's 0.6um design rules for their double layer metal, single polysilicon gate standard CMOS process. No performance changes are expected for these products. All product performance will meet the current datasheet specifications.

Tower Semiconductor is a high volume Silicon supplier for flash memory, image sensors, mixed signal and standard CMOS products. They are located in Migdal Haemek, Israel, and are an ISO9001/QS9000 certified facility.

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#### **RELIABILITY DATA SUMMARY:**

Reliability Test Results:

SC88A package, 1 lot ea. of 74VHC1GT00, 74VHC1G00, 74VHC1GT08:

Test	Conditions	Results (#fail/total SS)
High Temp Op Life	TA=150C for 504hrs	0/77, 0/77, 0/77
High Temp Bake	150C for 504 hrs	0/77, 0/77, 0/77
RSH	260C, 10 seconds	0/30, 0/30, 0/30
PC-Temp Cycle	-65/+150C for 500 cyc	0/77, 0/77, 0/77
PC-Autoclave	121C/100%RH/15psig for 96hrs	0/77, 0/77, 0/77
PC-HAST	131C/80%RH for 96 hrs	0/77, 0/77, 0/77
PC	168hrs 85C/85%, 3 IR at 260C	0/231, 0/231, 0/231

#### **ELECTRICAL CHARACTERISTIC SUMMARY:**

All product performance meets current datasheet specifications.

Data is available upon request.

CHANGED PART IDENTIFICATION: Devices shipped after WW27.

### AFFECTED DEVICE LIST (WITHOUT SPECIALS):

#### **PART**

MC74VHC1G03DFT1

MC74VHC1G03DFT2

MC74VHC1G03DTT1

MC74VHC1G04DFT1

MC74VHC1G04DFT1G

MC74VHC1G04DFT2

MC74VHC1G04DFT2G

MC74VHC1G04DTT1

MC74VHC1G07DFT1

MC74VHC1G07DFT1G

MC74VHC1G07DFT2

MC74VHC1G07DFT2G MC74VHC1G07DTT1

MC74VHC1G07DTT1G

MC74VHC1G14DFT1

MC74VHC1G14DFT1G

MC74VHC1G14DFT2

MC74VHC1G14DFT2G

MC74VHC1G14DTT1

MC74VHC1GT04DF2G

MC74VHC1GT04DFT1 MC74VHC1GT04DFT2

MC74VHC1GT04DTT1

MC74VHC1GT14DF2G MC74VHC1GT14DFT1

MC74VHC1GT14DFT2

MC74VHC1GT14DTT1

MC74VHC1GT50DF1G

MC74VHC1GT50DF2G

MC74VHC1GT50DFT1

MC74VHC1GT50DFT2

MC74VHC1GT50DTT1

NL17SZ06DFT2

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NL17SZ07DFT2 NL17SZ07DFT2G

NL17SZ17DFT2

NL17VHC1G07DTT1

NL17VHC1GT50DFT1

NLVVHC1GT04DFT2

NLVVHC1GT50DFT1

NLWVHC1G04

NLWVHC1GT04

NLWVHC1GT50

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